

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

1. (previously presented) A process for manufacturing a composite polymeric circuit protection device, said process comprising
  - (1) providing a polymeric assembly comprising
    - (a) providing first and second laminates, each of which comprises a laminar polymer element having two conductive surfaces,
    - (b) providing a pattern of conductive material on at least one of the conductive surfaces on one laminate;
    - (c) securing the laminates in a stack in a desired configuration by means of an adhesive, one conductive surface of each of the first and second laminates comprising an external conductive surface of the stack, and
    - (d) making a plurality of electrical connections between a conductive surface of the first laminate and a conductive surface of the second laminate; and
  - (2) subdividing the assembly into individual devices each of which comprises at least one electrical connection.
2. (currently amended) The A process according to claim 1, wherein the pattern in step (b) is formed by selectively removing a portion of conductive material from at least one of the conductive surfaces on one laminate.
3. (currently amended) The A process according to claim 1, which further comprises providing a pattern of conductive material on at least one of the external conductive surfaces.
4. (currently amended) The A process according to claim 3, wherein the pattern on the external conductive surface is formed by selectively removing a portion of conductive material from the external conductive surface.

5. (currently amended) The A process according to claim 3, wherein at least one of the patterned external conductive surfaces is at least partially covered with an insulating layer.
6. (currently amended) The A process according to claim 1, wherein an additional conductive layer is added to at least part of at least one of the external conductive surfaces.
7. (cancelled)
8. (currently amended) The A process according to claim 1, wherein at least one laminate is marked to provide a unique identification of orientation.
9. (currently amended) The A process according to claim 1, wherein the assembly comprises a third laminate.
10. (currently amended) The A process according to claim 2, wherein the selective removal of conductive material is accomplished by etching, milling, or stamping.
11. (cancelled)
12. (currently amended) The A process according to claim 1, wherein electrical connection is made between conductive surfaces of the first and second laminates in the stack by (i) forming an aperture which extends through the stack, and (ii) forming a conductive member within the aperture.
13. (currently amended) The A process according to claim 1, wherein the electrical connections are positioned so that the individual device comprises at least two electrical connections.
14. (currently amended) The A process according to claim 1, wherein the laminar polymer element in at least one of the laminates comprises a PTC conductive polymer composition.
15. (currently amended) The A process according to claim 14, wherein the laminar polymer element in each laminate comprises the same PTC conductive polymer composition.

16. (currently amended) The A process according to claim 14, wherein the laminar polymer element in each laminate comprises a different PTC conductive polymer composition.
17. (currently amended) The A process according to claim 1 wherein the assembly comprises three laminates, each of which comprises a PTC conductive polymer composition.
18. (currently amended) The A process according to claim 1, wherein at least one of the laminar polymeric elements comprises a ZTC conductive polymeric material or an NTC conductive polymeric material.
19. (currently amended) The A process according to claim 1, wherein at least one of the laminar polymeric elements comprises an insulating polymeric material.
20. (currently amended) The A process according to claim 3, wherein the patterns on the internal and external conductive surfaces are different.
21. (currently amended) The A process according to claim 1, wherein the individual devices are subdivided from the assembly using a saw, a shear, a blade, a wire, a waterjet, a snapping device, a laser, or a combination of these.
22. (currently amended) The A process according to claim 8, wherein the laminate markings which provide a unique identification of orientation also provide delineation for subdividing into individual devices.
23. (currently amended) The A process according to claim 1 wherein the conductive surface on each laminate comprises a metal foil.
24. Canceled.
25. Canceled
26. Canceled.
27. (currently amended) The A process according to claim 9 wherein the third laminate comprises a laminar polymer element having two conductive surfaces.